			1				P	
	1	2	3	4		5		6
	A	+C1 GND GND GND GND	VCC U2A 2 VIN VOUT 6 TRIM/NR 4 10µF GND 4 REF5025AIDGKR	2.5V +C12 C13 1µF				
	В	2.5V R4 0 R2 120 R1 120 R6 0 C 1000	2 VIN- + U1 INA333AIDGK Rg 100 8 Hit OU 6	Vout				
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Assembly Variant: 001 File: TIPD170_SCH.SchDoc http://www.ti.com/ Contact: http://www.ti.com/support © Texas Instruments 2015	D			Texas Instruments and/or its licensors do not warrant the acc specification or any information contained therein. Texas Inst	curacy or completeness of this ruments and/or its licensors do no	Designed for: PA - Linear Project: Strain Gauge in a Bridge Sheet Title: TIPD170	Mod. Date: 11/19/2015 Configuration Reference Des	Texas
				warrant that this design will meet the specifications, will be su any particular purpose, or will operate in an implementation.	uitable for your application or fit fo Texas Instruments and/or its	Assembly Variant: 001 File: TIPD170_SCH.SchDoc		http://www.ti.com
	1	2	3				٠ــــــــــــــــــــــــــــــــــــ	

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